

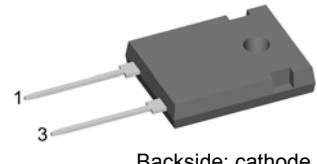
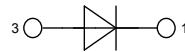
Standard Rectifier

Single Diode

V_{RRM} = 1600 V
I_{FAV} = 45 A
V_F = 1.23 V

Part number

DSI45-16A



Backside: cathode

Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

Applications:

- Diode for main rectification
- For single and three phase bridge configurations

Package:

- Housing: TO-247
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	Unit
V _{RRM}	max. repetitive reverse voltage	T _{VJ} = 25°C			1600	V
I _R	reverse current	V _R = 1600 V T _{VJ} = 25°C V _R = 1600 V T _{VJ} = 150°C			20 3	μA mA
V _F	forward voltage	I _F = 45 A I _F = 90 A T _{VJ} = 25°C I _F = 45 A I _F = 90 A T _{VJ} = 150°C			1.28 1.37 1.23 1.35	V
I _{FAV}	average forward current	rectangular d = 0.5 T _C = 130°C			45	A
V _{FO}	threshold voltage	for power loss calculation only	T _{VJ} = 175°C		0.81	V
r _F	slope resistance				9.1	mΩ
R _{thJC}	thermal resistance junction to case				0.55	K/W
T _{VJ}	virtual junction temperature		-40		175	°C
P _{tot}	total power dissipation	T _C = 25°C			270	W
I _{FSM}	max. forward surge current	t = 10 ms (50 Hz), sine t = 8,3 ms (60 Hz), sine t = 10 ms (50 Hz), sine t = 8,3 ms (60 Hz), sine	T _{VJ} = 45°C V _R = 0 V T _{VJ} = 150°C ¹ V _R = 0 V		480 518 408 441	A
I ² t	value for fusing	t = 10 ms (50 Hz), sine t = 8,3 ms (60 Hz), sine t = 10 ms (50 Hz), sine t = 8,3 ms (60 Hz), sine	T _{VJ} = 45°C V _R = 0 V T _{VJ} = 150°C ¹ V _R = 0 V		1152 1120 832 808	A ² s
C _J	junction capacitance	V _R = 400 V; f = 1 MHz	T _{VJ} = 25°C	18		pF

Release: PM _____, RD _____, QA _____, GM _____

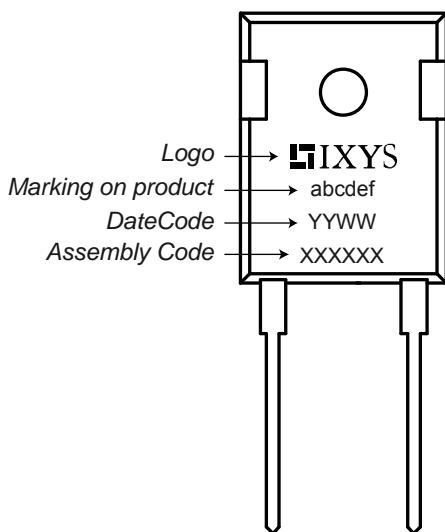
Date: PM _____, RD _____, QA _____, GM _____

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
I_{RMS}	RMS current	per pin ¹⁾			70	A
R_{thCH}	thermal resistance case to heatsink			0.25		K/W
T_{stg}	storage temperature		-55		150	°C
Weight				6		g
M_D	mounting torque		0.8		1.2	Nm
F_c	mounting force with clip		20		120	N

¹⁾ I_{RMS} is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

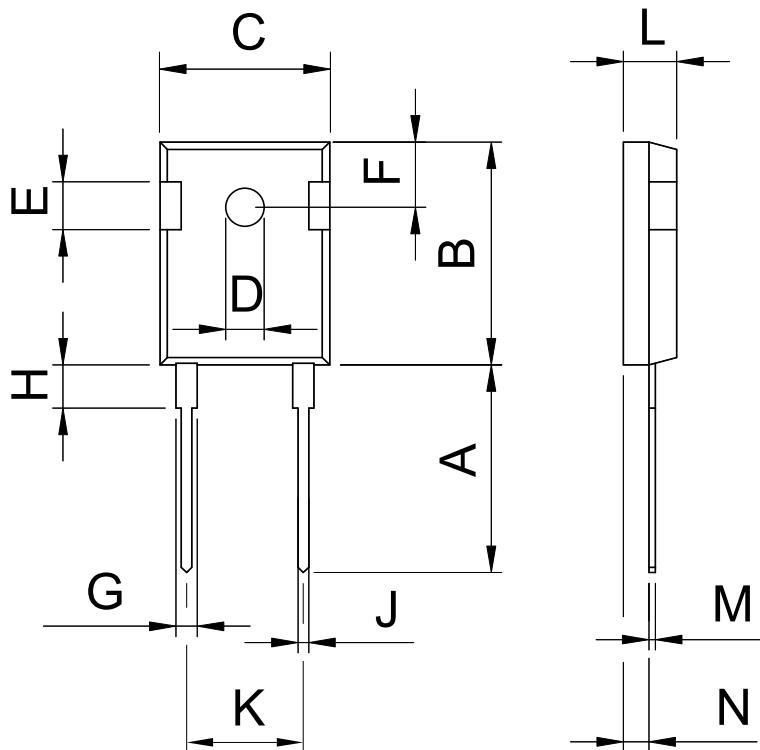
Product Marking



Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	DSI45-16A	DSI45-16A	Tube	30	471917

Similar Part	Package	Voltage class
DSI45-16AR	ISOPLUS247 (2)	1600
DSI45-12A	TO-247AD (2)	1200
DSI45-08A	TO-247AD (2)	800

Outlines TO-247



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102

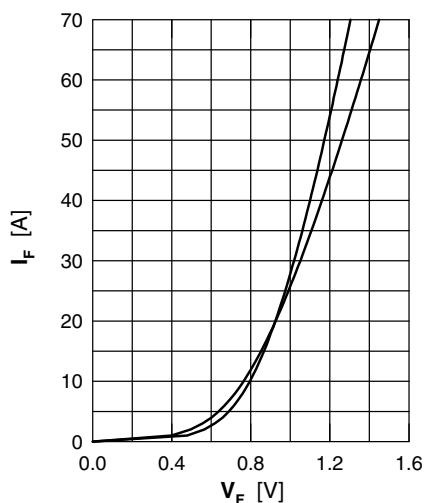


Fig. 1 Forward current versus voltage drop per diode

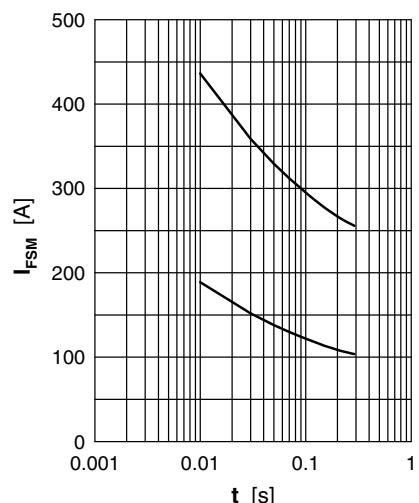


Fig. 2 Surge overload current

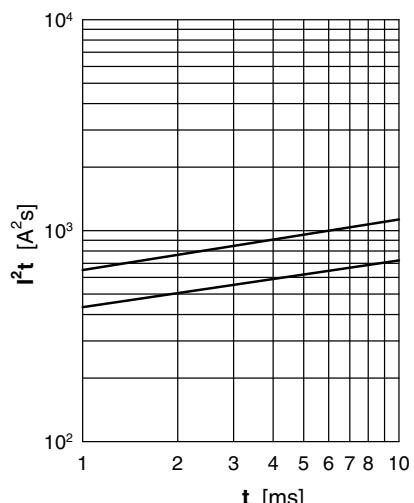
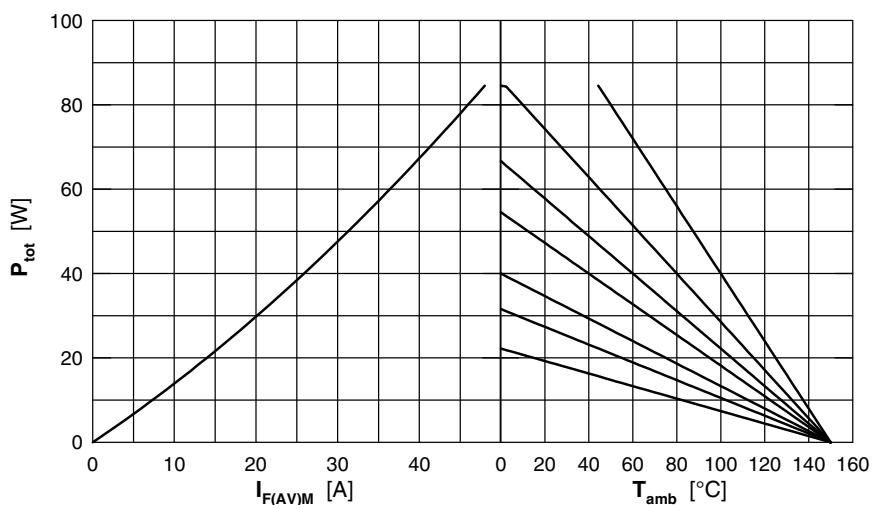
Fig. 3 I^2t versus time per diode

Fig. 4 Power dissipation vs. direct output current & ambient temperature, sine 180°

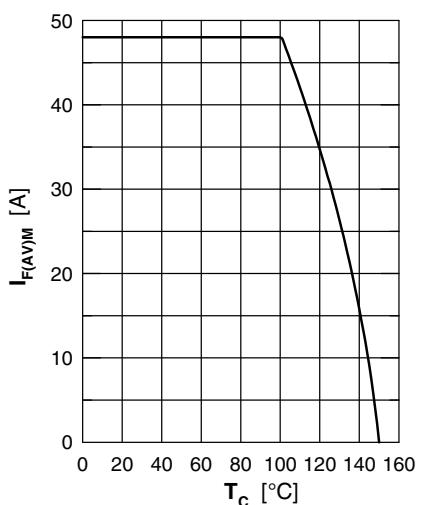


Fig. 5 Max. forward current versus case temperature, sine180°

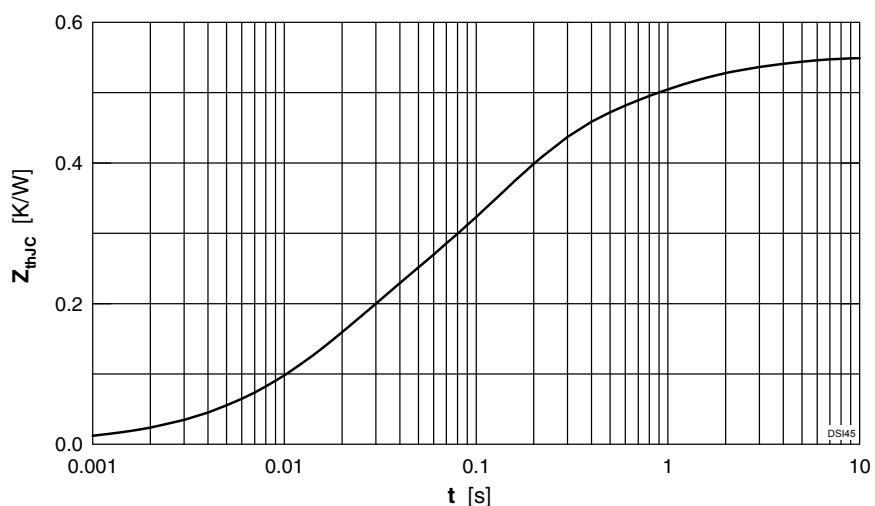


Fig. 6 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.1633	0.016
2	0.2517	0.118
3	0.0933	0.588
4	0.04167	2.6